

# RECEPTION SPONSORSHIP INFORMATION

## NAME OF EVENT

UV+EB Packaging Conference 2017 Presented by RadTech

# **EVENT LOCATION**

DoubleTree Philadelphia Airport - Philadelphia, PA

## **TABLE TOP HOURS**

## October 24, 2017

10:00 AM - 10:30 AM [Break] 12:00 PM - 1:00 PM [Lunch] 2:30 PM - 3:00 PM [Break]

4:00 PM - 5:00 PM [Reception]

\*\* Break Times Subject to Change \*\*

# **TABLE TOP SET-UP**

October 23, 2015

5:00 PM - 10:00 PM

# **EVENT PROFILE**

This one-day event takes place October 24, 2017 and consists of a conference and reception with table top sponsor exhibits. The conference program will be focused on UV+EB curing technology for packaging.

# **TABLE TOP SPECIFICATIONS**

- Each sponsor will receive one, six foot skirted table.
- No pop-up booths will be allowed

#### **TABLE TOP EXHIBIT FEES**

\$550 for RadTech Member Companies \$800 for Non-Member Companies

#### **EXHIBIT FEE INCLUDES**

- 1 Six Foot Skirted Table
- Complete attendee list with company and address following the show
- 1 Conference Admission
- Company Logo on Website & Conference Materials

## ATTENDEE PROFILE

UV+EB Packaging Conference will have attendees from the following industries:

- UV LED & UV
- Electron Beam
- Adhesives
- Consumer Goods
- Security Printing
- Converting
- Decorative Applications
- Plastics & Glass
- UV Inkjet
- Flexible Packaging
- Lithography
- Offset.
- ...and more

## **OUR ATTENDEES INCLUDE:**

- President / CEO / Owners
- Manufacturing Engineers
- Quality Control Managers
- Design Engineers
- Research & Development
- Technical Directors
- Brand Managers
- Plant Managers
- ...and more

# FOR MORE INFORMATION

Mickey Fortune

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# SPONSOR TABLE TOP CONTRACT October 24, 2017 DoubleTree Philadelphia Airport – Philadelphia, PA

1 SPONSOR INFORMATION				
Important: Please PRINT your compa	ny name exactly as you want	it to appear in all promotion	materials	
Company Name				
Address				
City	State	Zip/Postal Code	Country	
Telephone Number		Fax Number		
E-Mail	Compar	Company Web Address		
Name of Person to Receive all information				
2 SPONSORSHIP FEES				
□ RadTech Member \$550.00  Total Due:	☐ Non-Member \$800  Total Due:			
3 PAYMENT				
☐ Check made payable to RAD	TECH or Credit Card			
		curity Code	_ Expiration Date:/_	
4 PRODUCTS AND/OR SERVI	CES TO BE DISPLAYE	D		
Please list a description of the products/sen	vices that will be displayed in your	r table top exhibit:		
5 SIGNATURES				
We, the undersigned, do hereby apply for the this shall constitute a binding agreement be Packaging Conference 2017.	ne reservation of sponsor table top tween RADTECH and the unders	o space at UV+EB Packaging ( igned Sponsor for the rental of	Conference 2017. When executed by both said table top during the reception at UV+	n parties, ·EB
Name (Please print)		Authorized Signature Date		

# 6 CONTRACT VALIDATION

To validate this contract, please fill in all sections completely. Be sure to sign the agreement and return it with the full amount due for sponsorship:

RADTECH 6935 Wisconsin Avenue Suite 207 Chevy Chase, MD 20815 Fax: 240-209-2337